

#### Description

The STD17NF03LT4 uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =20A

 $R_{DS(ON)} < 25 m\Omega @ V_{GS} = 10V$ 

### Application

Battery protection

Load switch Uninterruptible power supply

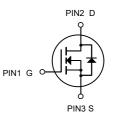
### Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
STD17NF03LT4	TO-252-2L	HXY MOSFET	2500

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage ±20		V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> 20		А
I₀@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> 15		А
Ідм	Pulsed Drain Current <sup>2</sup>	50	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	8.1	mJ
las	Avalanche Current	12.7	А
P₀@Tc=25°C	Total Power Dissipation <sup>4</sup>	20.8	W
Тятд	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-ambient <sup>1</sup>	62	°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup> 6		°C/W





N-Channel MOSFET



#### N-Channel Enhancement Mode MOSFET

Symbol	mbol Parameter Conditions		Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
∆BV <sub>DSS</sub> /∆T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I⊳=1mA		0.023		V/°C	
		V <sub>GS</sub> =10V , I <sub>D</sub> =10A		18	25		
Rds(on)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A		25	38	mΩ	
VGS(th)	Gate Threshold Voltage		1.0	1.2	2.5	V	
$\bigtriangleup V_{\text{GS(th)}}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-4.2		mV/°C	
	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	:0V , TJ=55°C		5	uA	
lgss	Gate-Source Leakage Current	$V_{GS}$ =±20V , $V_{DS}$ =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		5.5		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.3		Ω	
Qg	Total Gate Charge (4.5V)			4.9			
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		1.66		nC	
Qgd	Gate-Drain Charge	_		1.85			
Td(on)	Turn-On Delay Time			1.6			
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V ,		15.8		ns	
Td(off)	Turn-Off Delay Time	Rg=3.3		13			
Tf	Fall Time	I <sub>D</sub> =10A		4.8			
Ciss	Input Capacitance			416			
Coss	Output Capacitance			62		pF	
Crss	Reverse Transfer Capacitance	_		51			
ls	Continuous Source Current <sup>1,5</sup>				24	Α	
Іѕм	Pulsed Source Current <sup>2,5</sup>	$-V_{G}=V_{D}=0V$ , Force Current			50	Α	
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V	
trr	Reverse Recovery Time	IF=10A , dl/dt=100A/µs ,		8.7		nS	
Qrr	Reverse Recovery Charge	TJ=25°C		1.95		nC	
			1	1			

# Electrical Characteristics (T<sub>C</sub>=25<sup>°</sup>C unless otherwise noted)

Note :

1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2The data tested by pulsed , pulse width .The EAS data shows Max. rating .

3he test condition is V $\leq$  300us , duty cycle <sub>DD=25</sub> $\leq$ V,V 2%<sub>GS</sub> =10V,L=0.1mH,I<sub>AS</sub>=12.7A

4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



# STD17NF03LT4 N-Channel Enhancement Mode MOSFET

# **Typical Characteristics**

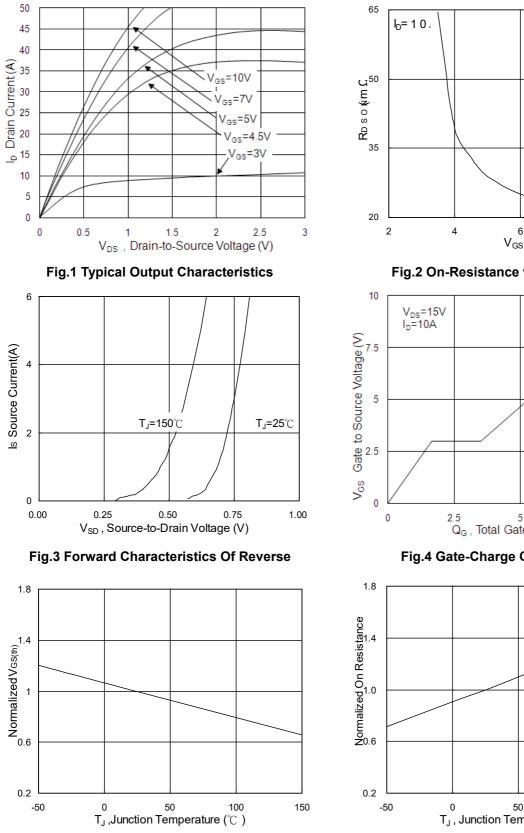


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

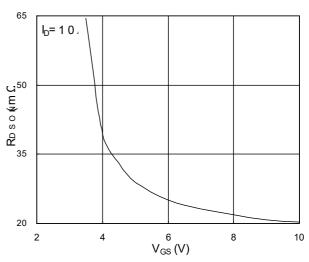
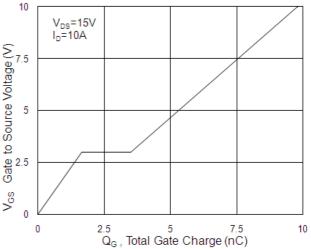


Fig.2 On-Resistance vs. Gate-Source



**Fig.4 Gate-Charge Characteristics** 

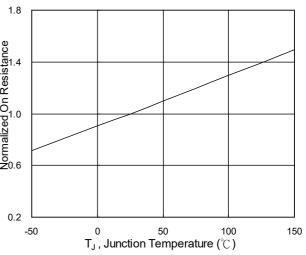
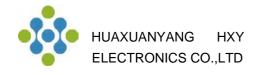


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



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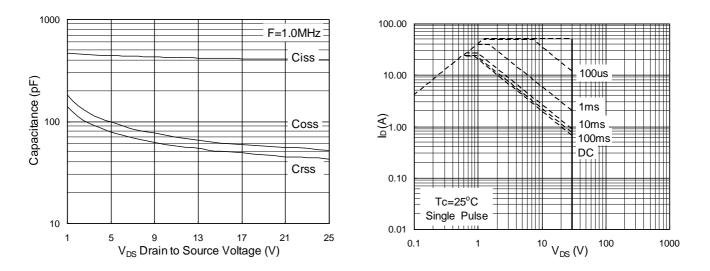


Fig.7 Capacitance

Fig.8 Safe Operating Area

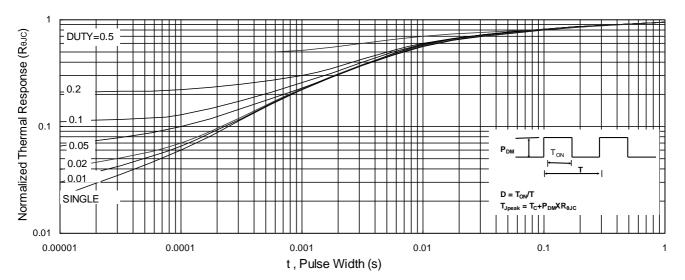


Fig.9 Normalized Maximum Transient Thermal Impedance

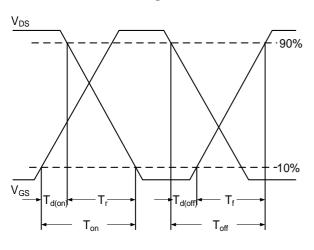


Fig.10 Switching Time Waveform

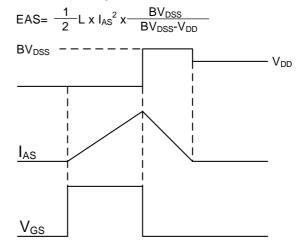
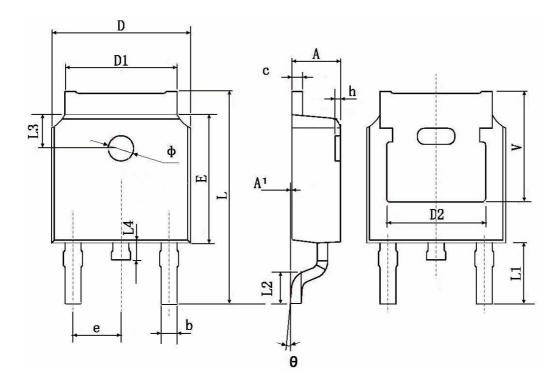


Fig.11 Unclamped Inductive Switching Waveform



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	TYP.	0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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